

SECTION 1 - SERVICING

1. Preventive Maintenance Procedures

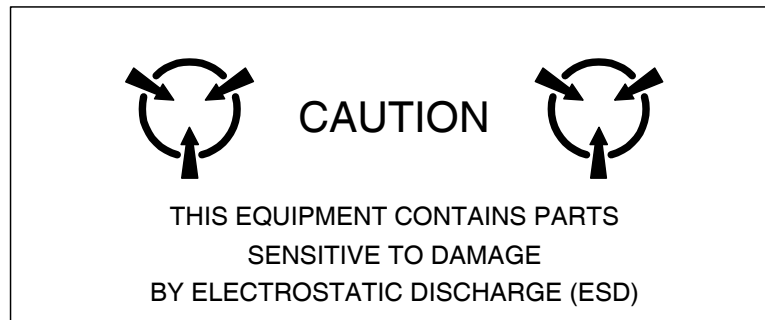
Contains routine maintenance instructions for cleaning and inspecting the Test Set.

CAUTION: DISCONNECT POWER FROM TEST SET TO AVOID POSSIBLE DAMAGE TO ELECTRONIC CIRCUITS.

A. External Cleaning

STEP	PROCEDURE
1.	Clean front panel, switches and display face with soft lint-free cloth. If dirt is difficult to remove, dampen cloth with water and mild liquid detergent.
2.	Remove grease, fungus and ground-in dirt from surfaces with soft lint-free cloth dampened (not wet) with isopropyl alcohol.
3.	Remove dust and dirt from connectors with soft-bristled brush.
4.	Cover connectors, not in use, with suitable dust cover to prevent tarnishing of connector contacts.
5.	Clean cables with soft lint-free cloth.
6.	Paint exposed metal surface to avoid corrosion.

B. Internal Cleaning



CAUTION: AVOID MOVING COMPONENTS ON CIRCUIT BOARDS OR DISASSEMBLING CONNECTORS NEEDLESSLY TO PREVENT POSSIBLE DAMAGE.

CAUTION: AVOID OPENING COMPLEX INTERNAL MODULES FOR THE SOLE PURPOSE OF CLEANING AND INSPECTION.

STEP	PROCEDURE
1.	Remove dust with hand-controlled dry air jet of 15 psi (1.054 kg/cm ²) and wipe internal chassis parts and frame with soft lint-free cloth moistened with alcohol.
2.	Clean switches and controls with contact cleaner.

C. Visual Inspection

STEP	PROCEDURE
1.	Inspect Chassis for: <ul style="list-style-type: none">● Tightness of sub-assemblies and chassis mounted connectors.● Corrosion or damage to metal surfaces.
2.	Inspect Capacitors for: <ul style="list-style-type: none">● Loose mounting, deformities or obvious physical damage.● Leakage or corrosion around leads.
3.	Inspect Connectors for loose or broken parts, cracked insulation and bad contacts.
4.	Inspect Controls for correct rotation.
5.	Inspect Circuit Boards for: <ul style="list-style-type: none">● Corrosion or damage to connectors.● Damage to mounted components including crystals and ICs.● Freedom from foreign material.
6.	Inspect Resistors for: <ul style="list-style-type: none">● Cracked, broken, charred or blistered bodies.● Loose or corroded soldering connections.
7.	Inspect Semiconductors for: <ul style="list-style-type: none">● Cracked, broken, charred or discolored bodies.● Seals around leads being in place and in good condition.
8.	Inspect Switches for: <ul style="list-style-type: none">● Loose levers, terminals and switch body contact to frame.● Bent or loose line switch contacts.
9.	Inspect Wiring for: <ul style="list-style-type: none">● Broken or loose ends and connections.● Proper dress relative to other chassis parts. <p>NOTE: Verify laced wiring is tight with ends securely tied.</p>